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#### **Current Transfer Ratio**

		sfer Ratio (%) /I <sub>F</sub> )	-
Classification (Note 1)	I <sub>F</sub> = 5mA, V <sub>CE</sub> :	= 5V, Ta = 25°C	Marking Of Classification
	Min	Max	
Blank	50	600	Blank ,Y <sup>∎</sup> ,YE,G,G <sup>■</sup> ,GR,B,BL,GB
Rank Y	50	150	YE, Y
Rank GR	100	300	GR, G, G■
Rank BL	200	600	BL, B
Rank GB	100	600	GB , GR , G, G■, BL , B
Rank YH	75	150	Y
Rank GRL	100	200	G
Rank GRH	150	300	G•
Rank BLL	200	400	В

Note 1: EX, Rank GB: TLP181 (GB)

Note: Application, type name for certification test, please use standard product type name, i, e TLP181 (GB): TLP181

Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit	
	Forward current	lF	50	mA	
	Forward current detating (Ta $\ge$ 89°C)	ΔI <sub>F</sub> /°C	-1.4	mA/°C	
	Pulse forward current (100µs pulse, 100pps)	IFP	1	A	
LED	Reverse voltage	VR	5	V	
_	Diode power dissipation	PD	100	mW	5
	Diode power dissipation derating (Ta $\ge$ 89°C)	$\Delta P_D/°C$	-2.8	mW/°C	
	Junction temperature	Tj	125	C.C	
	Collector-emitter voltage	V <sub>CEO</sub>	80	V	
	Emitter-collector voltage	V <sub>ECO</sub>		) v	
ctor	Collector current	IC	50	mA	$\bigcirc$
Detector	Collector power dissipation	Pc	150	mW	
	Collector power dissipation derating (Ta $\ge$ 25°C)	ΔP <sub>C</sub> /°C	-1.5	mW/°C	
	Junction temperature	Ţ	125	°C	UN.
Stor	rage temperature range	Tstg	-55 to 125	°C	YO/
Ope	erating temperature range	Topr	-55 to 110	C	
Lea	d soldering temperature (10 s)	Tsol	260	°C	
Tota	al package power dissipation	RT	200	mW	
Tota	al package power dissipation derating (Ta $\ge$ 25°C)	ΔP <sub>T</sub> /°C	-2.0	mW/°C	
Isola	ation voltage (AC, 60 s, R.H. ≤ 60 %) (Note 1)	BVs	3750	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Device considered a two-terminal device: Pin1, 3 shorted together and pins 4, 6 shorted together

#### **Recommended Operating Conditions**

Characteristic	Symbol	Min	Тур.	Max	Unit
Supply voltage	Vcc	_	5	48	V
Forward current	F	—	16	20	mA
Collector current	IC	-	1	10	mA

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

#### **Electrical Characteristics (Ta = 25°C)**

	Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward voltage	VF	I <sub>F</sub> = 10 mA	1.0	1.15	1.3	V
LED	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	—	10	μA
	Capacitance	Ст	V = 0 V, f = 1 MHz	X	30	_	pF
	Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> = 0.5 mA	80	4	_	V
	Emitter-collector breakdown voltage	V(BR)ECO	IE = 0.1 mA	7	_	_	V
Detector	Collector dark current	ICEO	V <sub>CE</sub> = 48 V, ( Ambient light below 1000 lx) (Note 1)	<u>)</u>	0.01 (2)	0.1 (10)	μA
		ICEO	V <sub>CE</sub> = 48 V, Ta = 85 °C, ( Ambient light below 1000 lx) (Note 1)	_	2 (4)	50 (50)	μA
	Capacitance (collector to emitter)	CCE	V = 0 V, f = 1 MHz	- 0	10	$\searrow$	pF

Note 1: Please use standard electric lamp to light up the device's marking surface.

### Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition		MIn	Тур.	Max	Unit
Current transfer ratio	JC/IF	IF = 5 mA, VcE = 5 V		50	_	600	%
	CAF	$\sim$	Rank GB	100	—	600	70
Saturated CTR	IC/IF(sat)	IF = 1 mA, V <sub>CE</sub> = 0.4 V Rank GB			60	_	%
			Rank GB	30			70
	$\sum$	IC = 2.4 mA, IF = 8 mA				0.4	
Collector-emitter saturation voltage	VCE(sat)	I <sub>C</sub> = 0.2 mA, I <sub>F</sub> = 1 mA		Ι	0.2		V
	$\mathcal{D}$	$(\overline{\Omega})$	Rank GB		_	0.4	
Off-state collector current	IC(off)	VF = 0.7V, VCE = 48 V		_	1	10	μA

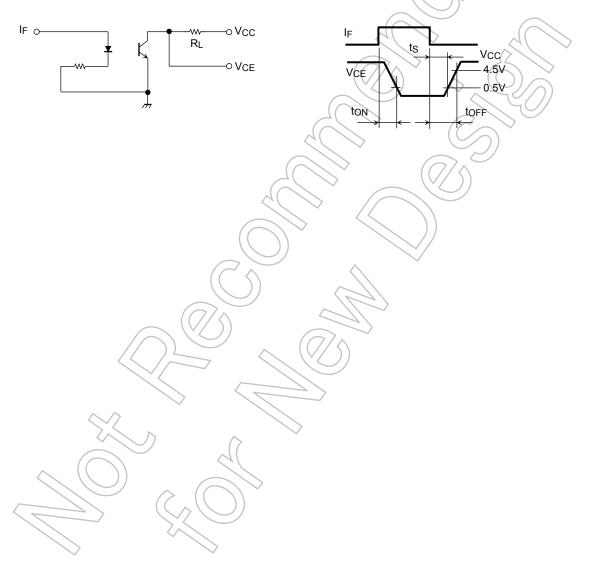
### Isolation Characteristics (Ta = 25°C)

Symbol	Test Condition	Min	Тур.	Max	Unit
Cs	VS = 0 V, f = 1 MHz	—	0.8	_	pF
Rs	V <sub>S</sub> = 500 V, R.H. ≤ 60 %	1×10 <sup>12</sup>	10 <sup>14</sup>	_	Ω
BVs	AC, 60 s	3750		_	Vrms
	Cs Rs	Cs         Vs = 0 V, f = 1 MHz           Rs         Vs = 500 V, R.H. $\leq 60 \%$	Cs         Vs = 0 V, f = 1 MHz            Rs         Vs = 500 V, R.H. $\leq 60 \%$ 1×10 <sup>12</sup>	Cs       Vs = 0 V, f = 1 MHz       -       0.8         Rs       Vs = 500 V, R.H. $\leq 60 \%$ 1×10 <sup>12</sup> 10 <sup>14</sup>	Cs       Vs = 0 V, f = 1 MHz       -       0.8       -         Rs       Vs = 500 V, R.H. $\leq 60 \%$ 1×10 <sup>12</sup> 10 <sup>14</sup> -

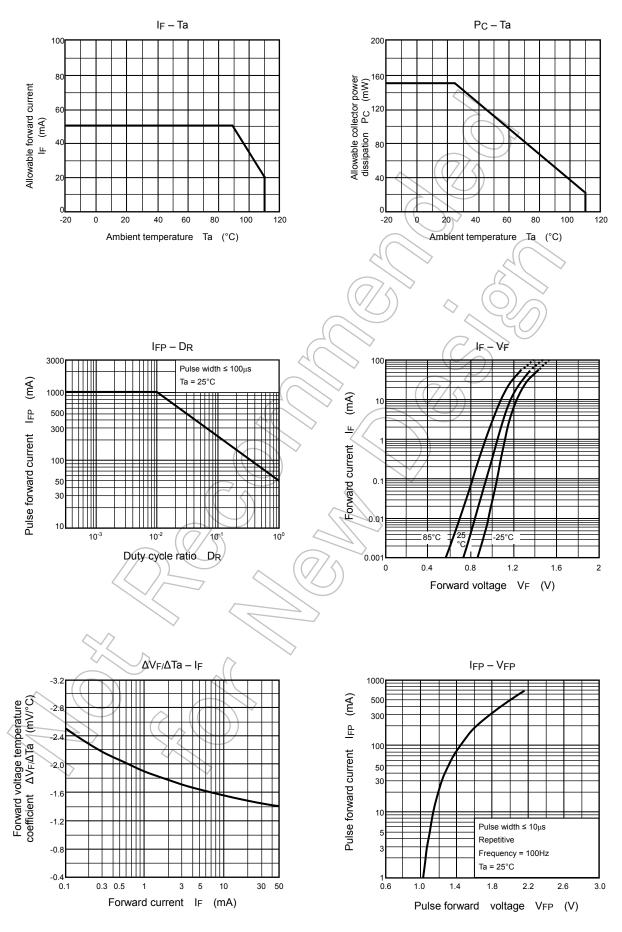
#### Switching Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Rise time	tr		—	2	_	·μs
Fall time	tf	V <sub>CC</sub> = 10 V, I <sub>C</sub> = 2 mA	_	3	-	
Turn-on time	ton	RL = 100 Ω	/	3		
Turn-off time	toff		$\langle \rangle$	3	_	
Turn-on time	ton		$(\mathcal{L})$	) <sup>2</sup>	-	
Storage time	ts		$\widetilde{2}$	25	-	μS
Turn-off time	toff		$\mathcal{Y}$	40	_	

#### Fig. 1 Switching time test circuit

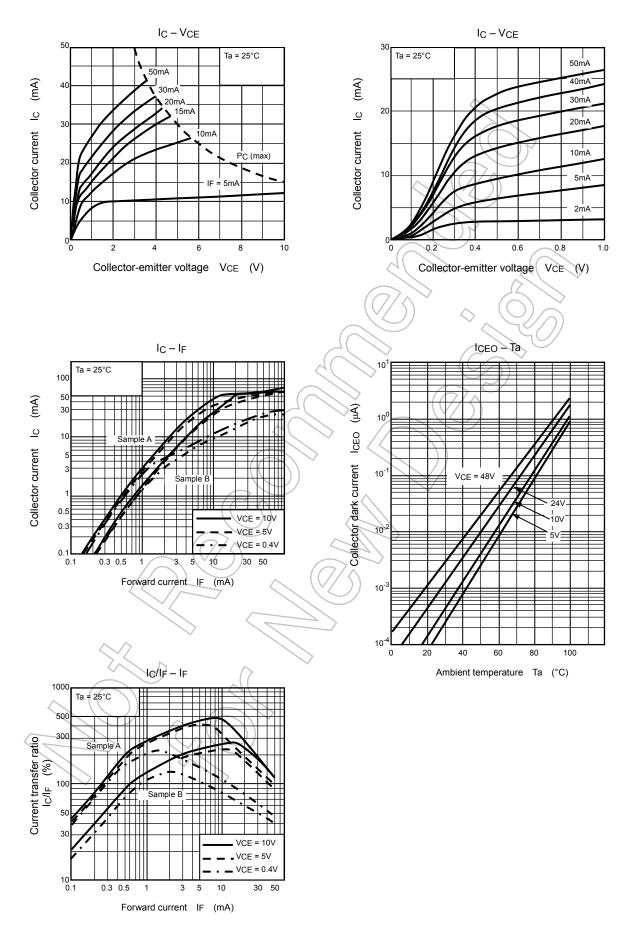


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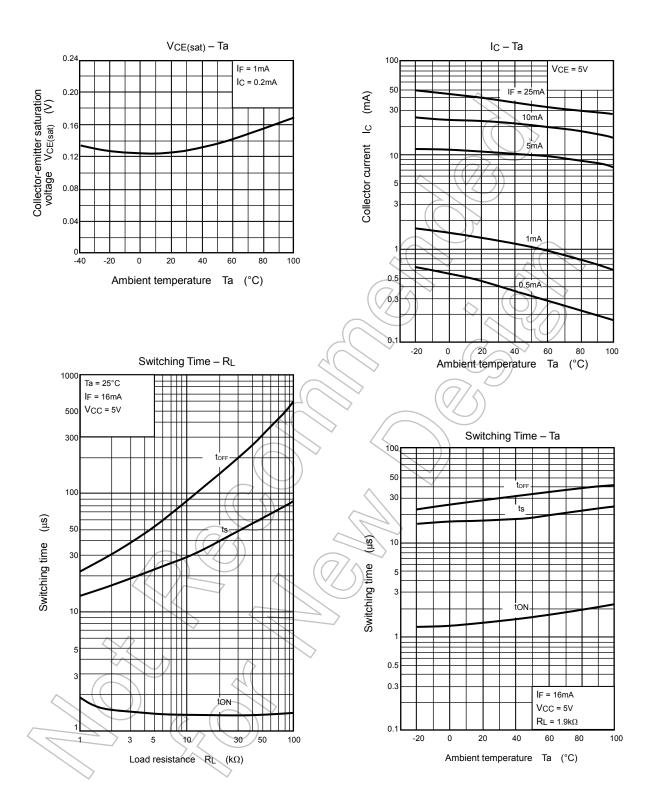
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